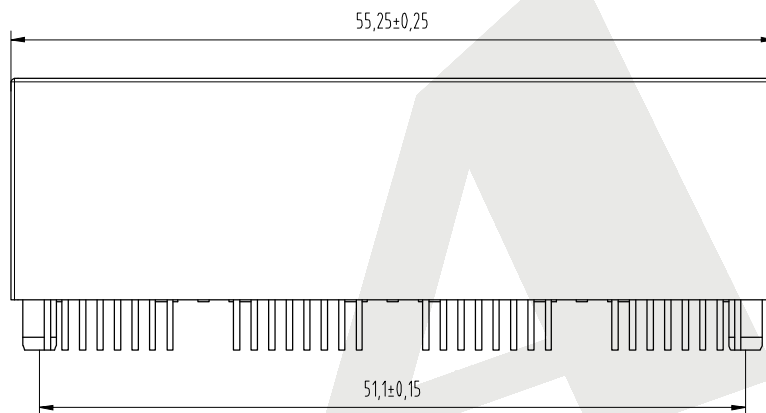
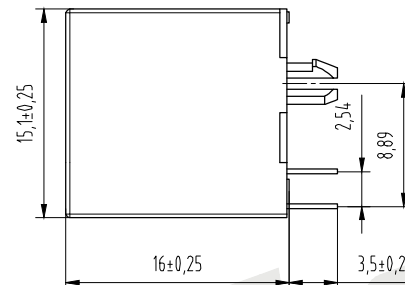
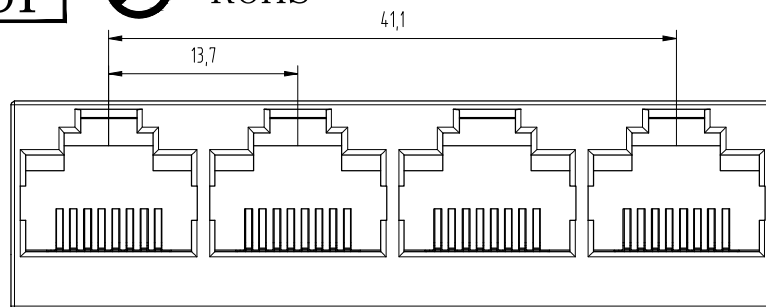


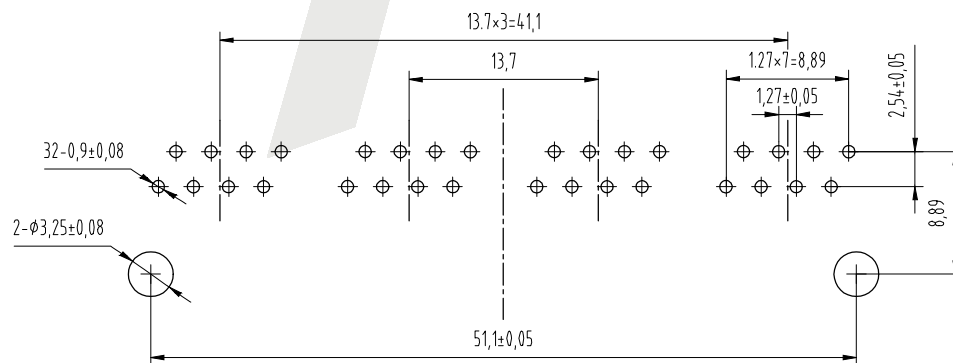
HSF



ROHS



PCB LAYOUT



PCB LAYOUT/TOP VIEW

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1μ~50μ"OVER NICKEL IN CONTACT AREA. 150μ" TIN PLATIN. OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30 MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVIORNMENTAL

- 1. STORAGE :-40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

Order code:

ATRJ5222 - 8P - 8C - X - A - C

- ①
- ②
- ③
- ④
- ⑤
- ⑥

- ① SERIES NO:
 - ② NUMBER OF POSITIONS (8P, 6P, 4P)
 - ③ NUMBER OF CONTACTS (8C, 6C, 4C)
 - ④ Contact Plating
 - ⑤ Shield
 - ⑥ Ports
- A:W/O Shield
 B:Half Shield
 C:Shield W/Eml
 D:Shield W/O Eml
 G0:Gold flash
 G1: 3U" Gold
 G2: 5U" Gold
 G3:10U" Gold
 G4:15U" Gold
 G5:30U" Gold
 SN:Tin
 A:1X1P
 B:1X2P
 C:1X4P
 D:1X5P
 E:1X6P
 F:1X8P

Unless Otherwise specified tolerance
 X. ±0.35 X.XX:±0.20
 X.X:±0.25 X.XXX:±0.15

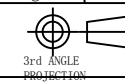


ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Sai	DATE 25/07/2019
CHECK BobYang	DATE 25/07/2019

TITLE: Modular Jack Top entry,
8P8C, 1X4Port Full Plastic

DRAWING NO: ATRJ5222-8P8C-X-A-C
 PRODUCT NO: ATRJ5222-8P8C-X-A-C



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		